

Title (en)  
HEAT PUMP DEVICE

Title (de)  
WÄRMEPUMPENVORRICHTUNG

Title (fr)  
DISPOSITIF DE POMPE À CHALEUR

Publication  
**EP 2407736 A1 20120118 (EN)**

Application  
**EP 10750810 A 20100309**

Priority  
• JP 2010053842 W 20100309  
• JP 2009060177 A 20090312

Abstract (en)  
A heat pump apparatus that is capable of suppressing an increase in the installation area therefor and volume thereof is provided. A heat pump apparatus (1) includes a compressor (5) that compresses refrigerant, a condenser (2) that liquefies the compressed refrigerant, and an evaporator (4) that evaporates the liquefied refrigerant, wherein the condenser (2) and the evaporator (4) are plate-type heat exchangers formed in rectangular cuboid shapes, and the condenser (2), which is a plate-type heat exchanger, and the evaporator (4), which is a plate-type heat exchanger, are disposed next each other.

IPC 8 full level  
**F25B 1/00** (2006.01); **F25B 1/04** (2006.01); **F25B 30/02** (2006.01); **F25B 31/00** (2006.01); **F25B 39/02** (2006.01); **F25B 39/04** (2006.01); **F25B 43/00** (2006.01); **F25B 43/02** (2006.01)

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**F25B 30/02** (2013.01 - EP US); **F25B 43/006** (2013.01 - EP US); **F25B 43/02** (2013.01 - EP US); **F25B 1/053** (2013.01 - EP US); **F25D 23/006** (2013.01 - EP US)

Cited by  
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